

RKR0303AKJ

Silicon Schottky Barrier Diode for Rectifying

REJ03G1738-0100

Rev.1.00

Nov 17, 2008

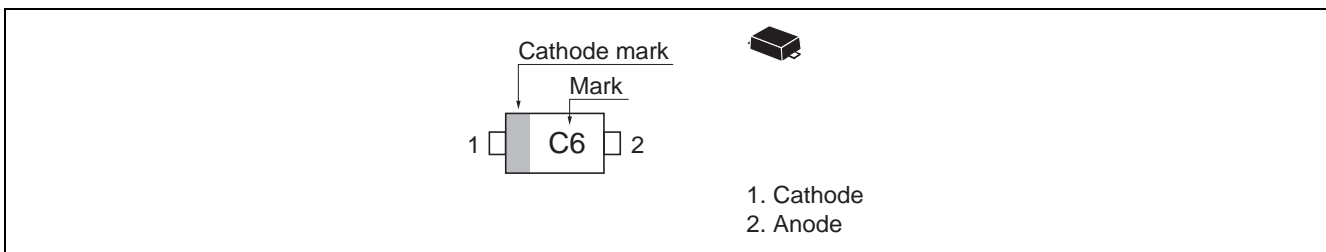
Features

- Low forward voltage drop and suitable for high efficiency rectifying.
- Thin Ultra small Resin Package (TURP) is suitable for compact and high-density surface mount design.

Ordering Information

Part No.	Laser Mark	Package Name	Package Code
RKR0303AKJ	C6	UFP	PWSF0002ZA-A

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Repetitive peak reverse voltage	V_{RRM}	30	V
Reverse voltage	V_R	30	V
forward current	I_F^{*1}	0.3	A
Non-Repetitive peak forward surge current	I_{FSM}^{*2}	1	A
Junction temperature	T_J	125	°C
Storage temperature	T_{stg}	-55 to +125	°C

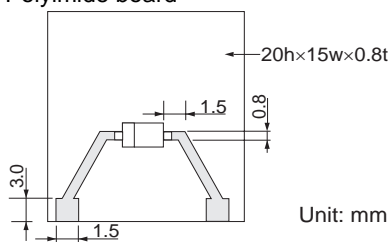
Notes: 1. See from Fig.4 to Fig.6.
2. 10 ms sine wave 1 pulse.

Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V_F	—	—	0.42	V	$I_F = 300 \text{ mA}$
Reverse current	I_R	—	—	200	μA	$V_R = 30 \text{ V}$
Thermal resistance	$R_{th(j-a)}$	—	600	—	°C/W	Polyimide board ^{*1}

Note: 1. Polyimide board



Note: In the UFP package, some lead is exposed because the tip of the lead is used as the cutting plane. Therefore, the solderability of the lead tip has been ignored. Please test and confirm before use.

Main Characteristic

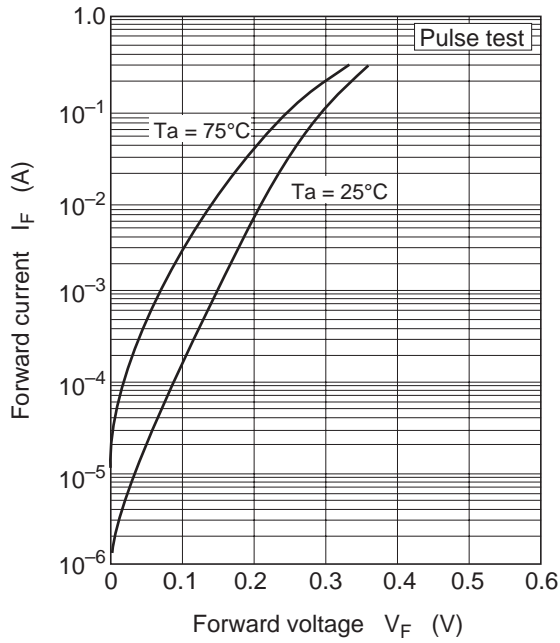


Fig.1 Forward current vs. Forward voltage

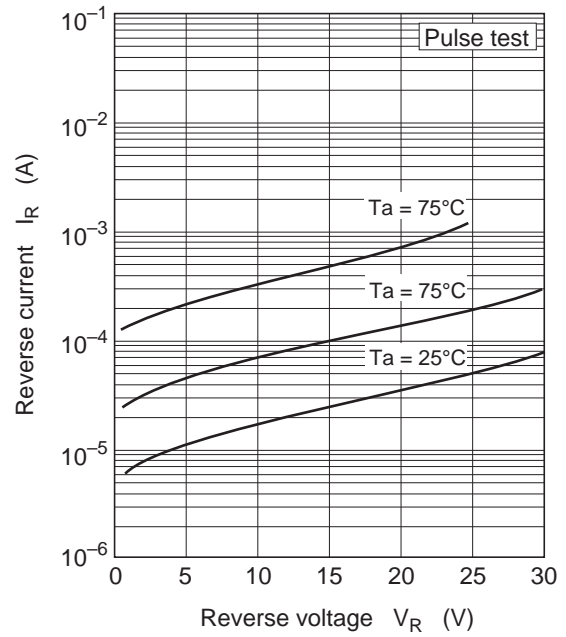


Fig.2 Reverse current vs. Reverse voltage

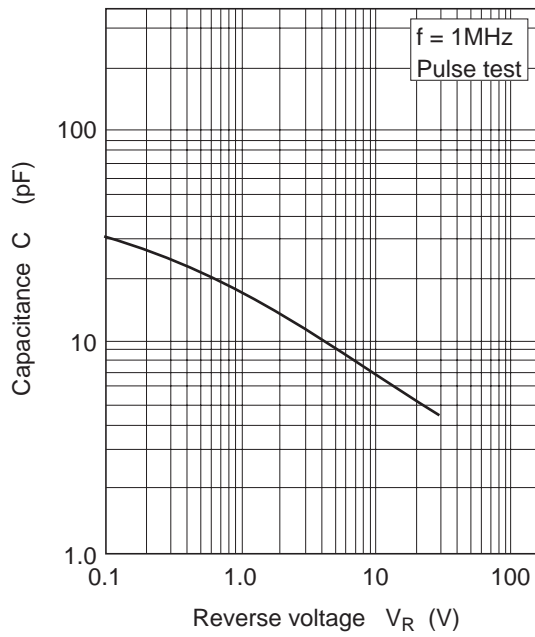


Fig.3 Capacitance vs. Reverse voltage

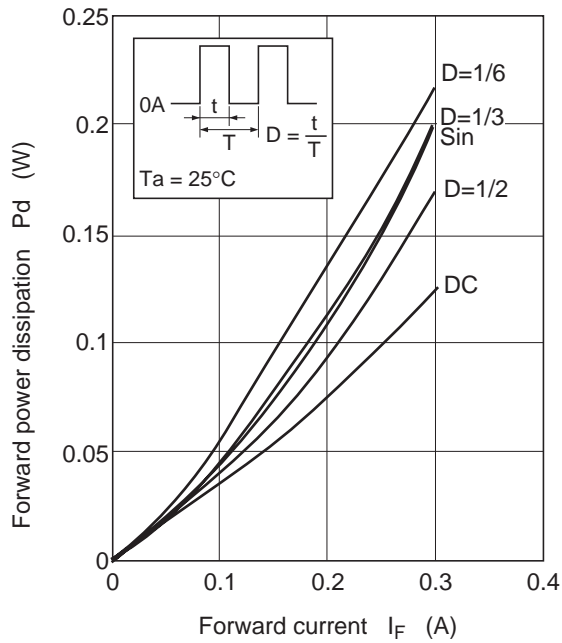


Fig.4 Forward power dissipation vs. Forward current

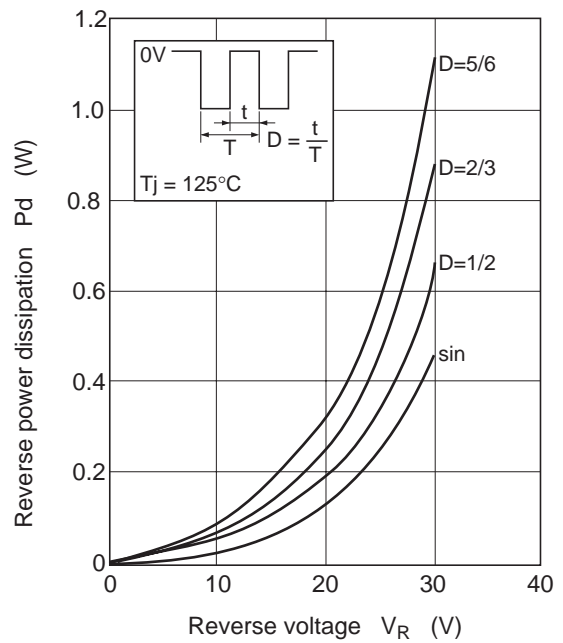


Fig.5 Reverse power dissipation vs. Reverse voltage

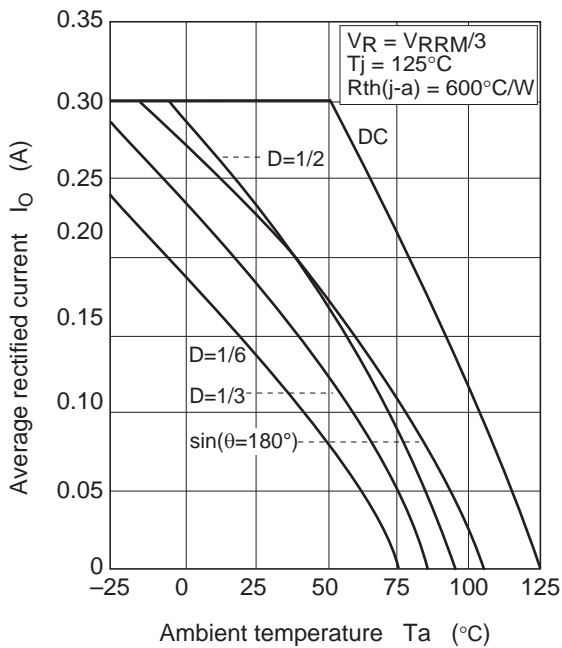
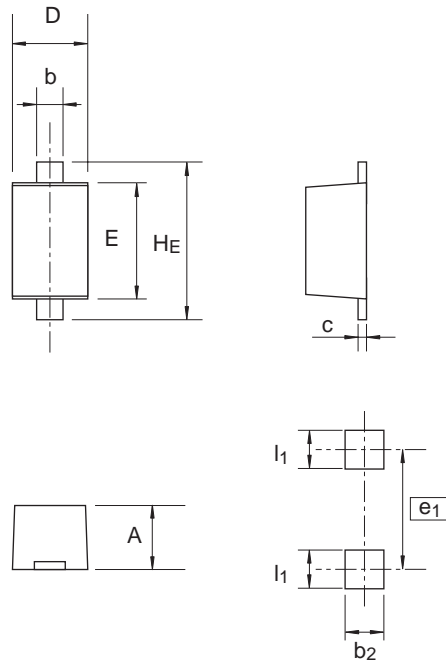


Fig.6 Average rectified current vs. Ambient temperature

Package Dimensions

Package Name	JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
UFP	SC-79	PWSF0002ZA-A	UFP / UFPV	0.0016g



Pattern of terminal position areas

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
A	0.50	0.60	0.70
b	0.25	0.30	0.35
c	0.08	0.13	0.18
D	0.70	0.80	0.90
E	1.10	1.20	1.30
HE	1.50	1.60	1.70
b2	—	0.80	—
e1	—	1.70	—
l1	—	0.60	—

Notes:

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